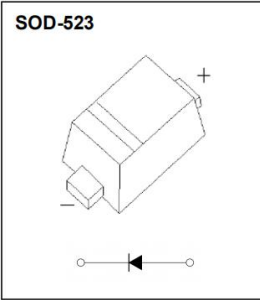


SOD-523 贴片塑封二极管

SOD-523 Plastic-Encapsulate Diodes



MARKING: B



特征 Features

- 小型表贴封装 Small Surface Mounting Type
- 低反向漏电 Low Reverse Leakage Current
- 高可靠性 High reliability

机械数据 Mechanical Data

- 封装: SOD-523 封装 SOD-523 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性 (TA = 25°C 除非另有规定)

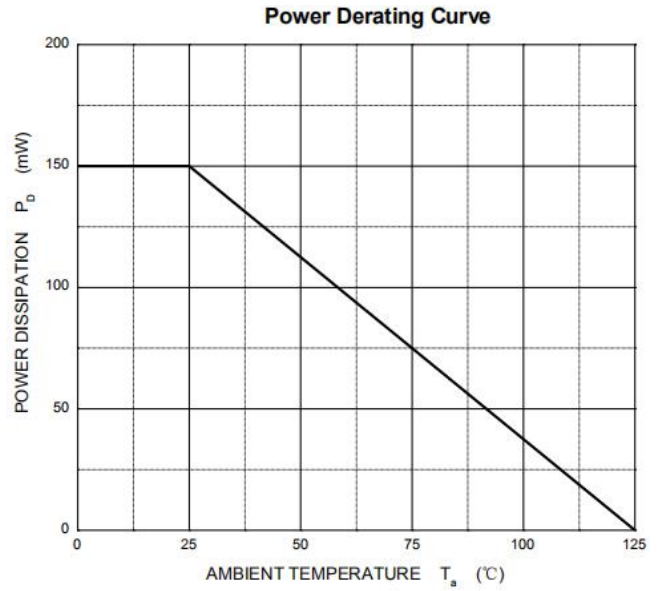
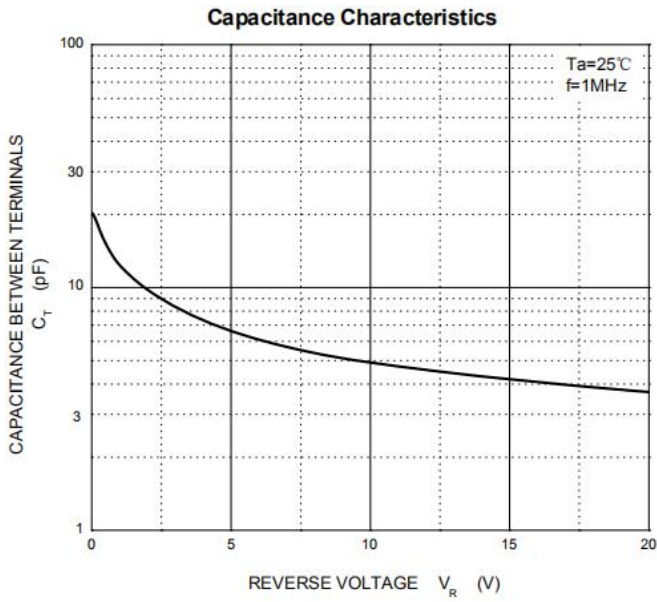
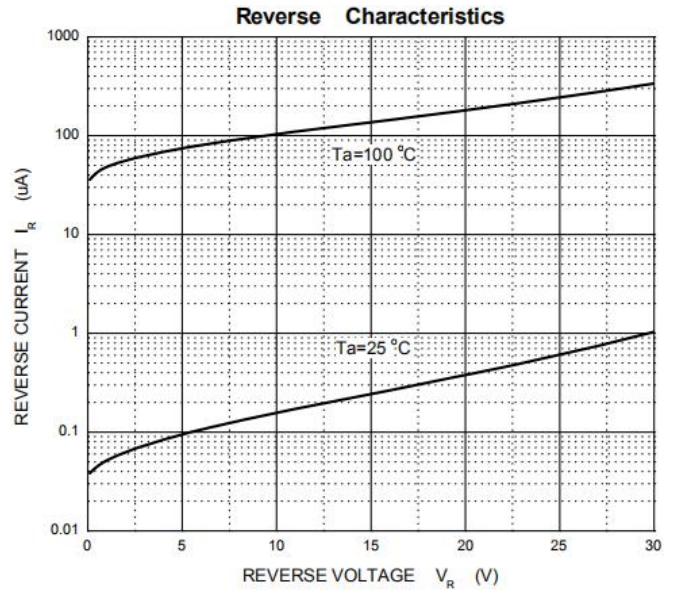
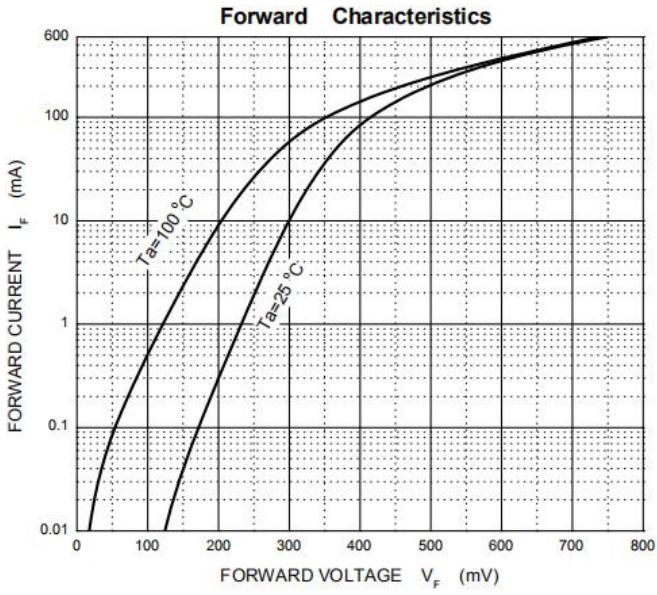
Maximum Ratings & Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
直流反向电压 DC Reverse Voltage	V _R	30	V
平均整流电流 Mean Rectifying Current	I _O	200	mA
尖峰正向不重复浪涌电流 Non-repetitive Peak Forward Surge Current @ t = 8.3ms	I _{FSM}	1.0	A
功率消耗 Power Dissipation	P _d	150	mW
结温 Junction temperature	T _j	125	°C
存储温度 Storage temperature range	T _{STG}	-55-+150	°C
热阻 Thermal Resistance from Junction to Ambient	R _{θJA}	667	°C/W

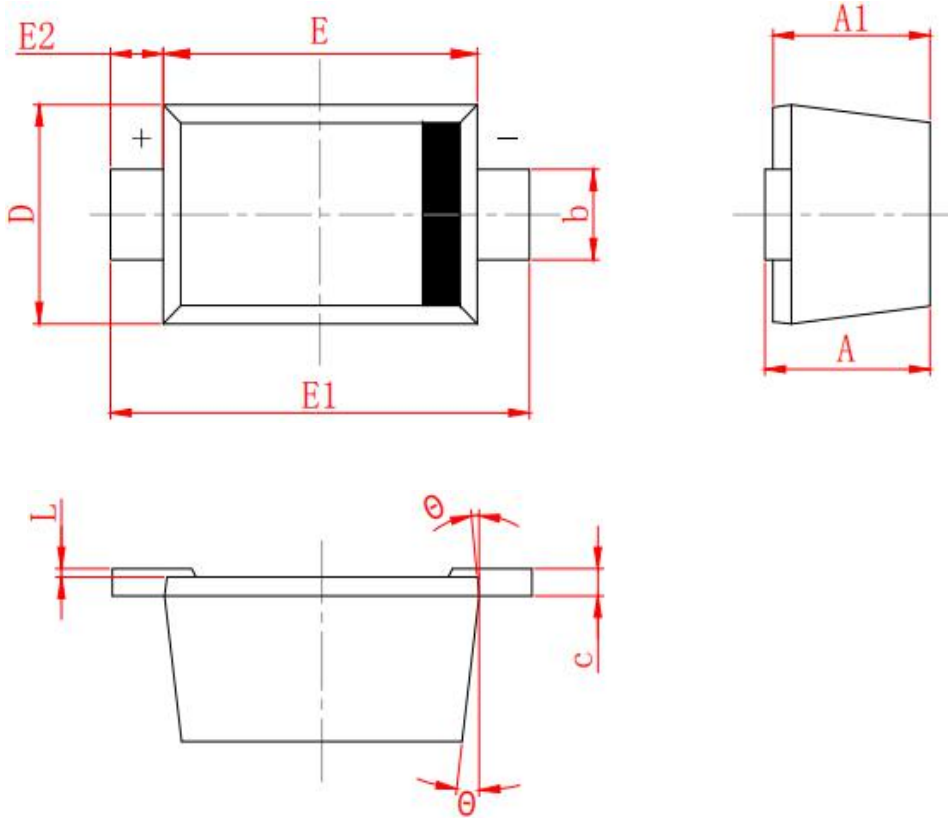
电特性 **Electrical Characteristics** (Ratings at 25°C ambient temperature unless otherwise specified).

符号 Symbols	参数 Parameter	测试条件 Test Condition	界限 Limits		单位 Unit
			Min	Max	
V _F	正向电压 Forward Voltage	I _F =200mA	---	0.6	V
I _R	反向漏电流 Reverse Current	V _R =10V	---	1	uA

典型特性 Typical Characteristics

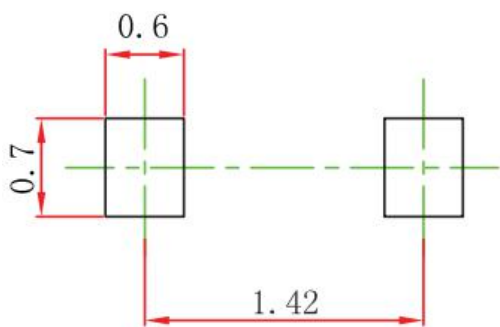


SOD-523封装外形尺寸图 SOD-523 Package Outline Dimensions



SYMBOL	MILLIMETER	
	MIN	MAX
A	0.530	0.730
A1	0.500	0.700
b	0.280	0.380
c	0.080	0.150
D	0.750	0.850
E	1.100	1.300
E1	1.500	1.700
E2	0.200 REF	
L	0.010	0.070
θ	7° REF	

SOD-523焊盘设计参考 SOD-523 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.